

SOT1932-1

FBGA417, fine-pitch ball grid array package, 417 terminals,
0.8 mm pitch, 17 mm x 17 mm x 2.58 mm body

3 July 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA417
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-06-2019
Manufacturer package code	98ASA01087D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
package height	-	2.58	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	417	-	



2 Package outline

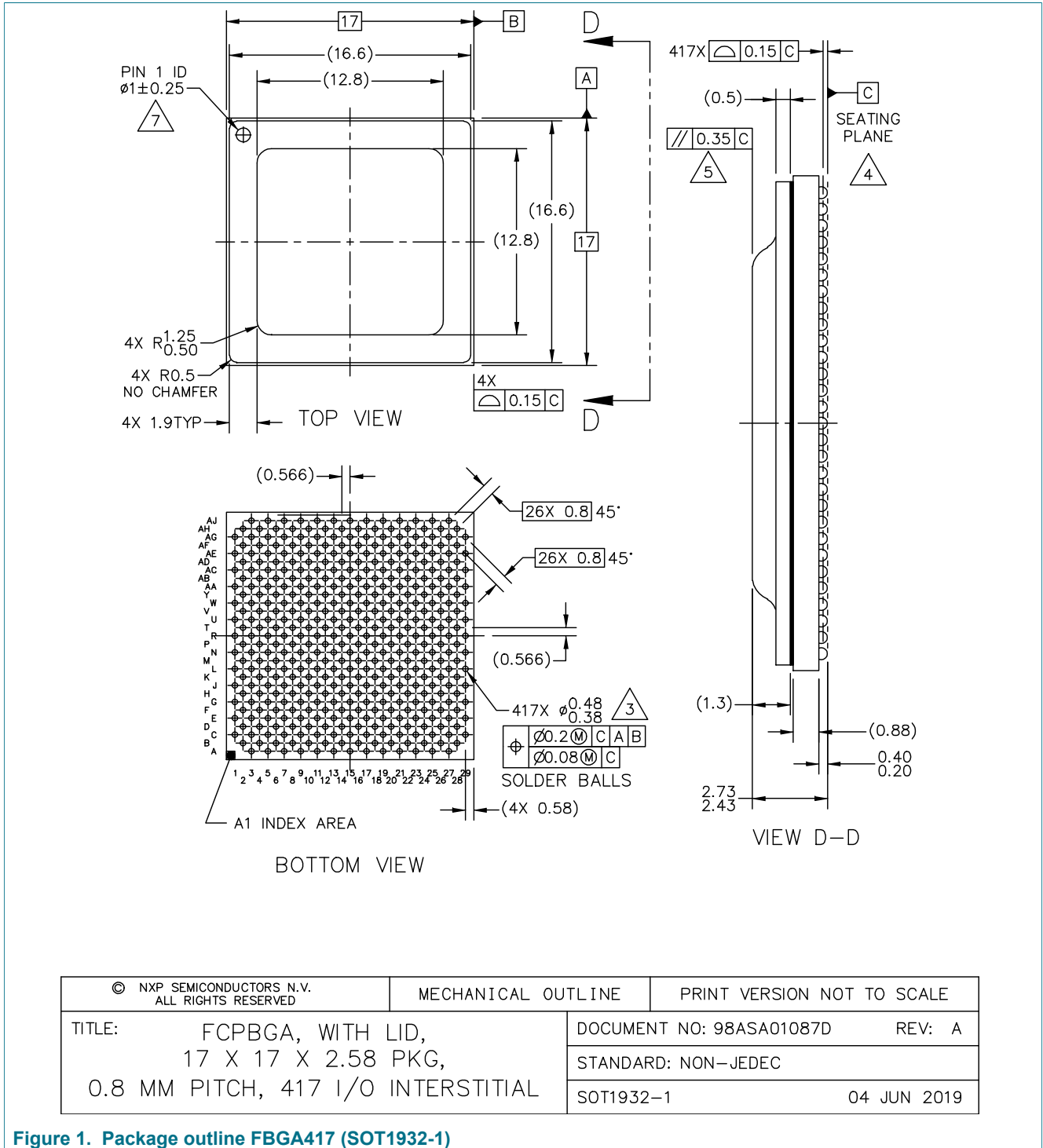


Figure 1. Package outline FBGA417 (SOT1932-1)

FBGA417, fine-pitch ball grid array package, 417 terminals, 0.8 mm pitch, 17 mm x 17 mm x 2.58 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN FOOT AREA.
8. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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TITLE: FCPBGA, WITH LID, 17 X 17 X 2.58 PKG, 0.8 MM PITCH, 417 I/O INTERSTITIAL	DOCUMENT NO: 98ASA01087D		REV: A
	STANDARD: NON-JEDEC		
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Figure 2. Package outline note FBGA417 (SOT1932-1)

3 Legal information

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